

WHAT IS CLAIMED IS

1. A heat sink assembly for use in an electrical apparatus having a printed circuit board having an electromagnetic device, and characterized in that said heat sink assembly comprises a first heat-dissipating piece disposed between said electromagnetic device and said printed circuit board for transferring the heat generated from said electromagnetic device away said printed circuit board.
2. The heat sink assembly according to claim 1 wherein said heat sink assembly further comprises a second heat-dissipating piece disposed on the edge of said printed circuit board and contacting with said first heat-dissipating piece for transferring the heat from said first heat-dissipating piece away said printed circuit board.
3. The heat sink assembly according to claim 2 wherein said first heat-dissipating piece is integrally formed with said second heat-dissipating piece.
4. The heat sink assembly according to claim 2 wherein said heat sink assembly further comprises a third heat-dissipating piece disposed on the top surface of said electromagnetic device for transferring the heat generated from said electromagnetic device away said printed circuit board.
5. The heat sink assembly according to claim 4 wherein said heat sink assembly further comprises a fourth heat-dissipating piece disposed on said printed circuit board and contacting with said third heat-dissipating piece for transferring the heat from said third heat-dissipating piece away said printed circuit board.
6. The heat sink assembly according to claim 5 wherein said third heat-dissipating piece and said fourth heat-dissipating piece are integrally formed.

7. The heat sink assembly according to claim 4 wherein said heat sink assembly further comprises a first isolation medium disposed between said electromagnetic device and said first heat-dissipating piece for isolating said first heat-dissipating piece from said electromagnetic device.

8. The heat sink assembly according to claim 7 wherein said first isolation medium is an adhesive tape.

9. The heat sink assembly according to claim 4 wherein said heat sink assembly further comprises a second isolation medium disposed between said electromagnetic device and said third heat-dissipating piece for isolating said third heat-dissipating piece from said electromagnetic device.

10. The heat sink assembly according to claim 9 wherein said second isolation medium is an adhesive tape.

11. The heat sink assembly according to claim 1 wherein said electrical apparatus electromagnetic device is a transformer.

12. A heat sink assembly for use in an electrical apparatus having a printed circuit board having an electromagnetic device, said heat sink assembly comprising:

a first heat-dissipating piece disposed between said electromagnetic device and said printed circuit board for transferring the heat generated from said electromagnetic device away said printed circuit board; and

a second heat-dissipating piece disposed on the edge of said printed circuit board and contacting with said first heat-dissipating piece for transferring the heat from said first heat-dissipating piece away said printed circuit board.

13. The heat sink assembly according to claim 12 wherein said first heat-dissipating piece is integrally formed with said second heat-dissipating piece.

14. The heat sink assembly according to claim 12 wherein said heat sink assembly further comprises a third heat-dissipating piece disposed on the top surface of said electromagnetic device for transferring the heat generated from said electromagnetic device away said printed circuit board.

15. The heat sink assembly according to claim 14 wherein said heat sink assembly further comprises a fourth heat-dissipating piece disposed on said printed circuit board and contacting with said third heat-dissipating piece for transferring the heat from said third heat-dissipating piece away said printed circuit board.

16. The heat sink assembly according to claim 15 wherein said third heat-dissipating piece and said fourth heat-dissipating piece are integrally formed.

17. The heat sink assembly according to claim 14 wherein said heat sink assembly further comprises a first isolation medium disposed between said electromagnetic device and said first heat-dissipating piece for isolating said first heat-dissipating piece from said electromagnetic device.

18. The heat sink assembly according to claim 17 wherein said first isolation medium is an adhesive tape.

19. The heat sink assembly according to claim 14 wherein said heat sink assembly further comprises a second isolation medium disposed between said electromagnetic device and said third heat-dissipating piece for isolating said third heat-dissipating piece from said electromagnetic device.

20. The heat sink assembly according to claim 19 wherein said second isolation medium is an adhesive tape.